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offering petition

S/N 10/023819

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Biju Chandran et al.	Examiner:	John Vigushin
Serial No.:	10/023819	Group Art Unit:	2827
Filed:	December 21, 2001	Docket:	884.A27US1
Title:	CHIP-JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN THE ADHERENTS AND SEMICONDUCTOR PACKAGE MADE THEREBY		
Assignee:	Intel Corporation	Customer No:	21186

PETITION TO WITHDRAW FROM ISSUE UNDER 37 CFR 1.313(c)(2)

Mail Stop 313(c)
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

The above-referenced patent application was allowed on July 8, 2003, and the Issue Fee was paid on October 8, 2003. Applicant respectfully requests that the above-identified patent application be withdrawn from Issue so that an Information Disclosure Statement may be submitted. Additionally, Applicant has enclosed a Request for Continued Examination transmittal and the requisite fee, which Petitioner wishes to enter even date herewith.

Authorization is hereby given to charge the petition fee of \$130.00 as set forth in § 1.17(h) which is required pursuant to 37 C.F.R. § 1.313(a), to Deposit Account 19-0743. Please charge any additional fees or credit overpayment to Deposit Account 19-0743.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

BIJU CHANDRAN ET AL.

By their Representatives,

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Date March 18, 2004

By Ann M. McCrackin
Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being hand-delivered to: US Patent and Trademark Office, 2011 South Clark Place, Customer Window, Mail Stop 313(c), Crystal Plaza Two, Lobby, Room 1B03, Arlington, VA 22202, on this 19TH day of March, 2004.

Name

Larry J. Hecker

Signature

Larry J. Hecker